

# PROTOTYPING ADAPTERS - BGA UNIVERSAL PROTOTYPING BOARDS

BGA Universal Prototyping Boards make it easy to adapt standard or high-density prototyping boards to a variety of BGA packages.

## FEATURES & BENEFITS

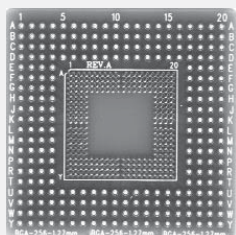
- Mountable 0.8mm, 1.0mm, 1.27mm lead pitch BGA/CSP up to 484 pin on 22X22/max
- Able to check all pins at outside holes, printed pin numbers for easy signal location
- Outer holes pitch: 2.54mm
- Solder resist treatment to prevent solder bridge
- Jumper pads available on two sides for custom wiring and additional circuitry
- 0.75mm, & 0.50mm lead pitch boards available upon request

## HOW TO ORDER

Please provide the following:

- IC Package Information: Manufacturer & Part Number, Pin Count, and/or Package Outline Drawing
- Prototyping Panel Type
- Determine Top Chip Interface Type: SMT Lands, Solder Tail Pin Receptacles, Production Socket, Zero Insertion Force Socket
- Determine Bottom Terminal Options: Wire Wrap Posts or Solder Tail Pin
- Adapter Application
- Quantity and Delivery Requirements

## EMULATION TECHNOLOGY RECOMMENDS



### BGA 256 Adapter

Users needing a BGA Surface Mount Adapter can also consider our adapters designed specifically for BGA 256 components. All pads break out to dedicated plated through holes. 1.00mm and 1.27mm lead pitch are available.

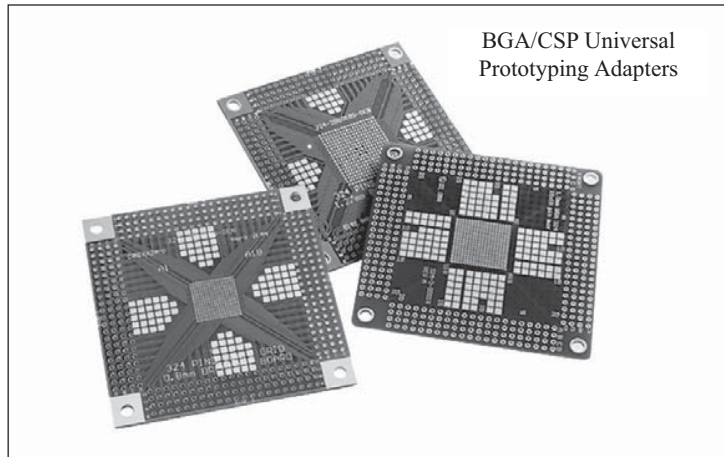
**Web Link: [www.1800adapter.com/001](http://www.1800adapter.com/001)**

**Try our Chip Quik® SMD Removal Kit**  
Speeds up SMD removal without requiring expensive equipment or risking the use of heat guns.

**Web Link: [www.1800adapter.com/046](http://www.1800adapter.com/046)**

For a complete list of prototyping adapter specifications, pricing and delivery information, please see:

**Web Link: [www.1800adapter.com/001](http://www.1800adapter.com/001)**



BGA/CSP Universal Prototyping Adapters

## Ordering Information Example

Package Code 324-6BG018S-GEN Standard Footprint  
 Pin Count | Lead Pitch | Grid Size (Square)  
 2 = 1.27mm   3 = 1.0mm   4 = 0.75mm  
 5 = .50mm   6 = 0.80mm   7 = 2.54mm

## Material Specifications

Package	0.8mm, 1.00mm, 1.27mm Lead Pitch
Material	Glass Epoxy (FR4)
Board Thickness	1.60mm
Copper Plate	Outside: 18mm, inside: 35mm
Plating	Gold Flash
Pin Number	Top side silk print, pin map available
Maximum Current	0.15 A per line

## KIT INCLUDES:

- Wire Wrap Post or Screw Machine Pin (available below)
- Prototyping Board
- Pin Map
- 3/4" Standoff (available below)
- Other patterns & sizes available upon request

## BGA / CSP

Pin Count	Lead Pitch	BGA Grid Size	Maximum .1" Grid Size	Description	Drawing#
324	0.80mm	SMT 18X18	29X29	324-6BG018S-GEN	F5939
324	1.00mm	SMT 18X18	29X29	324-3BG018S-GEN	F5938
324	1.27mm	SMT 18X18	29X29	324-2BG018S-GEN	F5937
484	1.00mm	SMT 22X22	41X41	484-3BG022S-GEN	F6977
484	0.80mm	SMT 22X22	41X41	484-6BG022S-GEN	F7052
676	1.00mm	SMT 26X26	26X26	676-3BG026S-GEN	F7092
900	1.00mm	SMT 30X30	40X40	900-3BG030S-GEN	F7020

Part #	Document	Description	Qty.
WWPost-40-PGA	PN1002	Wire Wrap Post - .025" Sq. Post	40 Per Strip
Header-Male-32	PN1039	Machine Screw Pin .018" Diameter	32 Per Strip
SPACER	F5784	3/4" Metal Standoff	1 Per